

PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT										
NATURE OF CONVEYANCE:	ASSIGNMENT										
CONVEYING PARTY DATA											
<table border="1"> <thead> <tr> <th>Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>JEAN-PIERRE COLINGE</td> <td>11/12/2013</td> </tr> <tr> <td>CHENG-TUNG LIN</td> <td>11/12/2013</td> </tr> <tr> <td>KUO-CHENG CHING</td> <td>11/12/2013</td> </tr> <tr> <td>CARLOS H. DIAZ</td> <td>11/12/2013</td> </tr> </tbody> </table>		Name	Execution Date	JEAN-PIERRE COLINGE	11/12/2013	CHENG-TUNG LIN	11/12/2013	KUO-CHENG CHING	11/12/2013	CARLOS H. DIAZ	11/12/2013
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<table border="1"> <tr> <td>Name:</td> <td>TAIWAN SEMICONDUCTOR MANUFACTURING COMPANY LIMITED</td> </tr> <tr> <td>Street Address:</td> <td>NO. 8, LI-HSIN ROAD, VI</td> </tr> <tr> <td>Internal Address:</td> <td>HSINCHU SCIENCE PARK</td> </tr> <tr> <td>City:</td> <td>HSINCHU</td> </tr> <tr> <td>State/Country:</td> <td>TAIWAN</td> </tr> </table>		Name:	TAIWAN SEMICONDUCTOR MANUFACTURING COMPANY LIMITED	Street Address:	NO. 8, LI-HSIN ROAD, VI	Internal Address:	HSINCHU SCIENCE PARK	City:	HSINCHU	State/Country:	TAIWAN
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PROPERTY NUMBERS Total: 1											
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CORRESPONDENCE DATA											
<p>Fax Number: (212)755-7306</p> <p>Phone: 212-326-3939</p> <p>Email: erosenfelder@JonesDay.com</p> <p><i>Correspondence will be sent via US Mail when the email attempt is unsuccessful.</i></p> <p>Correspondent Name: JONES DAY</p> <p>Address Line 1: 222 EAST 41ST ST</p> <p>Address Line 4: NEW YORK, NEW YORK 10017</p>											
ATTORNEY DOCKET NUMBER:	181877-625047										
NAME OF SUBMITTER:	MATTHEW W. JOHNSON										
Signature:	/Matthew W. Johnson/										

Date:

11/20/2013

Total Attachments: 2

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JOINT

ASSIGNMENT

WHEREAS, WE, JEAN-PIERRE COLINGE, CHENG-TUNG LIN, KUO-CHENG CHING and CARLOS H. DIAZ citizen of Belgium, the Republic of China and Colombia, having the mailing addresses listed as below.

JEAN-PIERRE COLINGE citizen of Belgium having a mailing address of 4F-2, No. 50, Dasyue Road, Hsinchu City, Taiwan residing at Hsinchu City, Taiwan;

CHENG-TUNG LIN citizen of the Republic of China having a mailing address of 5F., No. 6, Alley 39, Lane 152, Sec. 2, Jhongsing Rd., Jhudong Township, Hsinchu County 310, Taiwan residing at Hsinchu County, Taiwan;

KUO-CHENG CHING citizen of the Republic of China having a mailing address of 5F., No. 8-3, Guangming 9th Rd., Zhubei City, Hsinchu County 302, Taiwan residing at Hsinchu County, Taiwan;

CARLOS H. DIAZ citizen of Colombia having a mailing address of 1451 TODD Street, Mountain View, CA 94040, USA residing at CA, USA,

ASSIGNORS, are the inventors of the invention in "NANOWIRE MOSFET WITH DIFFERENT SILICIDES ON SOURCE AND DRAIN" for which we have executed an application for a Patent of the United States

- ☒ which is executed on ☒ even date herewith or ☐
☒ which is identified by Jones Day docket no. 181877-625047
☐ which was filed on October _____, 2013, Application No. _____
☐ We hereby authorize and request attorney(s) at Jones Day, to insert here in parentheses (Application number _____, filed _____) the filing date and application number of said application when known.

and WHEREAS, Taiwan Semiconductor Manufacturing Company Limited, a corporation organized and existing under the laws of Republic of China, and having an office for the transaction of business at No. 8, Li-Hsin Rd. VI, Hsinchu Science Park, Hsinchu, Taiwan, ASSIGNEE, is desirous of obtaining our entire right, title and interest in, to and under the said invention and the said application:

NOW, THEREFORE, for good and valuable consideration, the receipt of which is hereby acknowledged, we, the said ASSIGNORS, have sold, assigned, transferred and set over, and by these presents do hereby sell, assign, transfer and set over, unto the said ASSIGNEE, its successors, legal representatives and assigns, our entire right, title and interest in, to and under the said invention, and the said United States application and all divisions, renewals and continuations thereof, and all Patents of the United States which may be granted thereon and all reissues and extensions thereof, and all applications for industrial property protection, including, without limitation, all applications for patents, utility models, and designs which may be filed for said invention in any country or countries foreign to the United States, together with the right to file such applications and the right to claim for the same the priority rights derived from said United States application under the Patent Laws of the United States, the International Convention for the Protection of Industrial Property, or any other international agreement or the domestic laws of the country in which any such application is filed, as may be applicable; and all forms of industrial property protection, including, without limitation, patents, utility models, inventors' certificates and designs which may be granted for said invention in any country or countries foreign to the United States and all extensions, renewals and reissues thereof; and all right to sue for infringement including past infringement.

AND WE HEREBY authorize and request the Commissioner for Patents and any Official of any country or countries foreign to the United States, whose duty it is to issue patents or other evidence or forms of industrial property protection on applications as aforesaid, to issue the same to the said ASSIGNEE, its successors, legal representatives and assigns, in accordance with the terms of this instrument.

AND WE HEREBY covenant and agree that we have full right to convey the entire interest herein assigned, and that we have not executed, and will not execute, any agreement in conflict herewith.

AND WE HEREBY further covenant and agree that we will communicate to the said ASSIGNEE, its successors, legal representatives and assigns, any facts known to us respecting said invention, and testify in any legal proceeding, sign all lawful papers, execute all divisional, continuing, reissue and foreign applications, make all rightful oaths, and generally do everything possible to aid the said ASSIGNEE, its successors, legal representatives and assigns, to obtain and enforce proper protection for said invention in all countries.

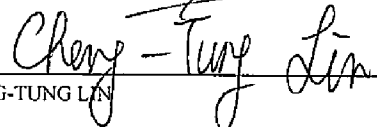
IN TESTIMONY WHEREOF, We hereunto set our hands and seals the day and year set opposite our respective signatures.

Date 12 November, 2013


JEAN-PIERRE COLINGE

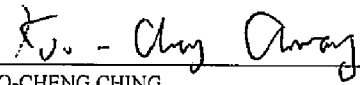
L.S.

Date 11/12/2013, 2013


CHENG-TUNG LIN

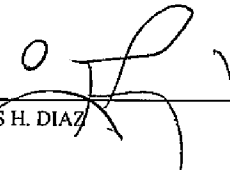
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KUO-CHENG CHING

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CARLOS H. DIAZ

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